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Laser-based Micro- and Nanoprocessing IX

Udo Klotzbach
Kunihiko Washio
Craig B. Arnold
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The CID Number appears on each page of the manuscript. The complete citation is used on the first page, and an abbreviated version on subsequent pages.

Contents

vii *Authors*
ix *Conference Committee*

LASER MICRO-STRUCTURING AND PROCESSING I

9351 02 **Smart laser micro-welding of difficult-to-weld materials for electronic industry (Invited Paper)** [9351-1]

9351 03 **Picosecond laser fabrication of micro cutting tool geometries on polycrystalline diamond composites using a high-numerical aperture micro scanning system** [9351-2]

9351 04 **Experimental and modelling investigations into the laser ablation with picosecond pulses at second harmonics** [9351-3]

9351 06 **Femtosecond fiber laser welding of PMMA** [9351-5]

LASER MICRO-STRUCTURING AND PROCESSING II

9351 0B **High volume transfer of high viscosity silver pastes using laser direct-write processing for metallization of c-Si cells** [9351-11]

9351 0C **Multilayer based lab-on-a-chip-systems for substance testing** [9351-12]

9351 0D **Enhancing vapor generation at a liquid-solid interface using micro/nanoscale surface structures fabricated by femtosecond laser surface processing** [9351-13]

9351 0E **Fundamental investigations of ps-laser burst-mode on common metals for an enhanced ablation process** [9351-14]

DIRECT WRITE PROCESSING, ABLATION, AND SURFACE MODIFICATION I

9351 0G **Femtosecond laser-based production of 3D micro- and nano- devices in transparent substrate: a step toward system-materials (Invited Paper)** [9351-16]

9351 0H **Dynamics of optically excited tungsten and silicon for ripples formation** [9351-17]

9351 0J **Superhydrophobic metallic surfaces functionalized via femtosecond laser surface processing for long term air film retention when submerged in liquid** [9351-19]

9351 0K **Electrochemical and kinetic studies of ultrafast laser structured $LiFePO_4$ electrodes** [9351-65]

9351 0L **Influence of pulsed Nd^{3+}: YAG laser beam profile and wavelength on micro-scribing of copper and aluminum thin films** [9351-20]

9351 0M **Effects of burst mode on transparent materials processing** [9351-21]

9351 0N **Laser processing of glass fiber reinforced thermoplastics with different wavelengths and pulse durations** [9351-22]

LASER MICRO-STRUCTURING AND PROCESSING III

9351 0Q **Metal deep engraving with high average power femtosecond lasers** [9351-25]

9351 0S **Metal mirrors with metal-dielectric HR-coating for ultrashort laser pulses applied in scanner applications** [9351-27]

DIRECT WRITE PROCESSING, ABLATION, AND SURFACE MODIFICATION II

9351 0U **Design and fabrication of sub-wavelength annular apertures for femtosecond laser machining** [9351-29]

9351 0V **Enhancing direct laser patterning of Si wafers by polystyrene films** [9351-30]

ADVANCED 1D TO 3D ADDITIVE PROCESSES

9351 0W **Present status and future outlook of selective metallization for electronics industry by laser irradiation to metal nanoparticles (Invited Paper)** [9351-31]

9351 0Y **Laser forward transfer of solder paste for microelectronics fabrication** [9351-33]

9351 10 **Diffractive beam shaping for enhanced laser polymer welding** [9351-35]

9351 11 **Laser sintering of silver nano-particles inks printed on paper substrates** [9351-36]

LARGE AREA MICRO/NANO STRUCTURING, LASER INTERFERENCE PATTERNING

9351 12 **Surface structuring of metals and non-metals for printing tools and embossing dies with an ultrafast ps-laser machining system (Invited Paper)** [9351-37]

9351 13 **Towards 3D laser nano patterning in polymer optical materials (Invited Paper)** [9351-38]

9351 14 **Direct Laser Interference Patterning (DLIP) technique applied to the development of optical biosensors based on biophotonic sensing cells (BICELLS)** [9351-39]

9351 15 **To use or not to use (direct laser interference patterning), that is the question** [9351-40]

9351 16 **Fabrication of highly efficient transparent metal thin film electrodes using Direct Laser Interference Patterning (Green Photonics Award Paper)** [9351-41]

9351 17 **Formation of Laser Induced Periodic Surface Structures (LIPSS) on Ti upon double fs pulse exposure** [9351-42]

HIGH-SPEED LASER BEAM ENGINEERING SYSTEMS FOR HIGH-POWER ULTRA-SHORT PULSED LASER

9351 18 **Ultrafast laser processing and metrology for consumer applications (Invited Paper)** [9351-43]

9351 19 **Nanosecond laser-induced ablation and laser-induced shock wave structuring of polymer foils down to sub-µm patterns** [9351-44]

9351 1A **Direct growth of patterned graphene on SiC(0001) surfaces by KrF excimer-laser irradiation** [9351-45]

ADVANCED LASER STRUCTURING FOR ENERGY STORAGE AND CONVERSION

9351 1C **Analytical model of the laser ablation mechanism of lithium-ion battery coatings (Invited Paper)** [9351-48]

9351 1D **Manufacturing of advanced Li(NiMnCo)O_2 electrodes for lithium-ion batteries** [9351-49]

9351 1E **Surface micro-structuring of intercalation cathode materials for lithium-ion batteries: a study of laser-assisted cone formation** [9351-50]

9351 1F **Femtosecond laser patterning of lithium-ion battery separator materials: impact on liquid electrolyte wetting and cell performance** [9351-51]

LASER MICRO-STRUCTURING AND PROCESSING IV

9351 1I **Investigation on the effect of ambient and beam profile in annealing and texturing of amorphous silicon thin films by pulsed Nd^{3+}:YAG laser** [9351-54]

9351 1J **Super hydrophobic surface of polytetrafluoroethylene fabricated by picosecond laser and phenomenon of total internal reflection underwater** [9351-55]

9351 1K **Thin glass processing with various laser sources** [9351-56]

POSTER SESSION

9351 1N **Laser micro-engineering of functionalized cyclic olefin polymers for microfluidic applications** [9351-59]

9351 1O **Generation of laser-induced periodic surface structures in indium-tin-oxide thin films and two-photon lithography of ma-N photoresist by sub-15 femtosecond laser microscopy for liquid crystal cell application** [9351-60]

9351 1Q **Investigation of double-pulse femtosecond laser induced breakdown spectroscopy of polymethyl methacrylate (PMMA)** [9351-62]

9351 1R **High performance light trapping structures for Si-based photoelectronics fabricated by hybrid picosecond laser irradiation and chemical corrosion** [9351-63]

9351 1T **Nanosecond laser-induced nanostructuring of thin metal layers and dielectric surfaces** [9351-66]

9351 1V **Laser based microstructuring of polymer optical fibers for sensors optimization** [9351-68]

Authors

Numbers in the index correspond to the last two digits of the six-digit citation identifier (CID) article numbering system used in Proceedings of SPIE. The first four digits reflect the volume number. Base 36 numbering is employed for the last two digits and indicates the order of articles within the volume. Numbers start with 00, 01, 02, 03, 04, 05, 06, 07, 08, 09, 0A, 0B...0Z, followed by 10-1Z, 20-2Z, etc.

Afshar, Maziar, 1O
Alexander, Dennis R., 0D, 0J
Ancona, Antonio, 06
Anderson, Troy P., 0D, 0J
Andersson, H., 11
Athanasekos, Loucas, 1V
Auyeung, Ray C.Y., 0Y
Bagga, Komal, 1N
Balliu, E., 11
Bayer, L., 19
Bellouard, Yves, 0G
Berger, J., 14, 15
Bergfeldt, T., 1E
Beyer, E., 15
Boerner, Paul, 04
Bourgeade, A., 0M
Brabazon, Dermot, 1N
Bruening, Stephan, 12
Busek, Mathias, 0C
Cao, Wenshen, 1J
Cao, Zhitao, 1Q
Casquel, R., 14
Charipar, Nicholas A., 0Y
Chen, Y., 0B
Cheng, Guanghua, 0H
Chimier, B., 0M
Chung, Ming-Han, 0U
Collins, Adam R., 1K
Colombier, Jean-Philippe, 0H
Damm, C., 0S
Dani, S., 14
Dematteo-Caulier, O., 0M
De Rosa, Andrea, 06
Di Niso, Francesca, 06
Dold, Claus, 03
Dreisow, F., 0S
Duchateau, G., 0M
Eberhardt, R., 0S
Eberle, Gregory, 03, 04
Eckhardt, S., 16
Ehrhardt, M., 19, 1T
El Sachat, Alexandros, 1V
Engholm, M., 11
Engisch, L., 19
Faucon, M., 0Q
Feili, Dara, 1O
Franke, C., 0S
Franke, Volker, 0C
Furukawa, Kazuaki, 1A
Gaudiuso, Caterina, 06
Gemini, Laura, 17
Gogos, George, 0D
Gotcu-Freis, P., 0K
Grünzner, Stefan, 0C
Gubler, U., 10
Gupta, Sanjay, 0L
Haghizadeh, Anahita, 0V
Hänel, N., 0E
Hashida, Masaki, 17
Hattori, Masakazu, 1A
Hennig, Guido, 12
Hernandez, A.L., 14
Herrmann, T., 0E
Hibino, Hiroki, 1A
Höenninger, C., 0M, 0Q
Holgado, M., 14
Hsu, Kuan-Yu, 0U
Hummelgård, M., 11
Hund, J., 1E
Ikenoue, Hiroshi, 1A
Inoue, Shunsuke, 17
Javaux Léger, C., 0M
Ji, Lingfei, 1J, 1R
Jiang, Yijian, 1J, 1R
Kaiser, N., 0S
Kämmer, H., 0S
Kellar, Jon J., 0V
Kim, Heungsoo, 0Y
Kling, R., 0M, 0Q
Klöppel, M., 1T
Klotzbach, Udo, 0C, 0N
Klötzer, Madlen, 1O
König, Karsten, 1O
Krupop, B., 0N
Kruse, Corey, 0D
Kunze, T., 15
L´huillier, J. A., 0E
Laguna, M., 14
Lang, V., 15
Langheinrich, D., 14
Lasagni, A.F., 14, 15, 16
Lauzurica, S., 0B
Lavin, A., 14
Lee, Chih-Kung, 0U
Lhuillier, J.A., 0E
Li, Chen, 0H
Li, Pengbo, 0J
Limpouch, Jiri, 17

Lin, Zhenyuan, 1R
Loeser, M., 16
Lopez, J., 0M
Lorenz, P., 19, 1T
Lucis, Michael J., 0J
Lugarà, Pietro Mario, 06
Lv, Xiaozhan, 1R
Mangang, M., 0K
Martìnez Vàzquez, Rebeca, 06
Mathews, Scott A., 0Y
Mathur, Anil C., 0L
McCann, Ronán, 1N
Milne, David, 1K
Mincuzzi, G., 0Q
Mishchik, K., 0M
Miyasaka, Yasuhiro, 17
Mocek, Tomas, 17
Molpeceres, C., 0B
Morales, M., 0B
Morin, F., 0Q
Mottay, E., 0M, 0Q
Müller, S., 0S
Müller-Meskamp, L., 16
Munoz-Martin, D., 0B
Murazawa, Naoki, 18
Nakashiba, S., 02
Nammi, Srinagalakshmi, 0L
Ndao, Sidy, 0D
Niemöeller, A., 1F
Nishi, Norio, 02
Nishii, Takaya, 17
Nolte, S., 0S
O'Connor, Gerard M., 1K
Okada, A., 02
Okamoto, Y., 02
Olin, H., 11
Osellame, Roberto, 06
Otón, A., 14
Perrie, Walter, 13
Peterson, Jacob, 0V
Pfleging, W., 0K, 1D, 1E, 1F
Piqué, Alberto, 0Y
Prieto, Camilo, 1K
Pröll, J., 1D, 1E, 1F
Raab, C., 10
Rakebrandt, J.-H., 1D
Rauschenberger, J., 10
Risse, S., 0S
Riziotis, Christos, 1V
Robertz, B., 1F
Roch, T., 15
Roth, Nick, 0J
Sakabe, Shuji, 17
Sakagawa, T., 02
Santamaría, B., 14
Sanza, F.J., 14
Schäfer, M., 1F
Schilling, N., 0N
Schlegel, R., 0S
Schmieder, Benjamin, 1C
Schmieder, Florian, 0C
Schmitz, B., 1F
Schürmann, M., 0S
Schwaller, P., 1T
Scully, Patricia J., 13
Seidel, Helmut, 1O
Seifert, H. J., 0K, 1D, 1F
Shield, Jeffrey E., 0J
Siebold, M., 16
Skupin, S., 0M
Smyrek, P., 1D, 1E, 1F
Sonntag, Frank, 0C
Sriram, R., 1I
Stalcup, Apryll, 1N
Steinkopf, R., 0S
Stoian, Razvan, 0H
Stolze, M., 0E
Straub, Martin, 1O
Takahashi, Kunimitsu, 18
Takamura, Makoto, 1A
Terry, Benjamin, 0J
Torge, M., 1F
Tung, Yen-Chun, 0U
Vainos, Nikolaos A., 1V
Vasa, Nilesh J., 0L, 1I
Vasileiadis, Miltiadis, 1V
Vázquez, Mercedes, 1N
Vidhya, Y. Esther Blesso, 1I
Vogler, D., 10
Volpe, Annalisa, 06
Wang, Cong, 1Q
Wang, Mengmeng, 1Q
Wang, Peng, 1Q
Wang, Sumei, 1Q
Watanabe, Akira, 0W
Wegener, Konrad, 03, 04
Wilson, Chris, 0D
Wu, Yan, 1J, 1R
Yang, Haeyeon, 0V
Zandonadi, Germana, 04
Zhang, Hao, 0H
Zhao, Yan, 1J
Zimmer, K., 19, 1T
Zuhlke, Craig A., 0D, 0J

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4 Direct Write Processing, Ablation, and Surface Modification I
Wilhelm Pfleging, Karlsruher Institut für Technologie (Germany)

5 Laser Micro-Structuring and Processing III
Rainer Kling, ALPhANOV (France)

6 Direct Write Processing, Ablation, and Surface Modification II
Craig B. Arnold, Princeton University (United States)

7 Advanced 1D to 3D Additive Processes
Antonio Ancona, CNR-Istituto di Fotonica e Nanotecnologie (Italy)

8 Large Area Micro/Nano Structuring, Laser Interference Patterning
Tim Kunze, Fraunhofer IWS Dresden (Germany)

9 High-Speed Laser Beam Engineering Systems for High-Power Ultra-Short Pulsed Laser
Akira Watanabe, Tohoku University (Japan)

10 Advanced Laser Structuring for Energy Storage and Conversion
Yongfeng Lu, University of Nebraska-Lincoln (United States)

11 Laser Micro-Structuring and Processing IV
Andreas E. H. Oehler, JDSU Ultrafast Lasers AG (Switzerland)